

SA88010RS22-J00 Silicon PIN Infrared Photodiode

General Description

SA88010RS22-J00 is a PIN photodiode with high speed and high photo sensitivity in an optical SMD2015 package. The sensitive area of chip is 1 mm^2 .

Applications

- Automotive sensors
- Industrial electronics

Features

Package type: Optical SMD2015

• Dimensions: 2.0mmx1.5mmx0.6mm (LxWxH)

• Peak sensitivity occurs with 870nm wavelength

• Fast rising and falling speed

AEC-Q102 Qualified

Absolute Maximum Ratings (T_A=+25°C)

Symbol	Parameter	Min	Max	Unit
T_{OP}	Operation temperature	-40	100	°C
$T_{ m stg}$	Storage temperature	-40	100	°C
V_R	Reverse voltage		20	V
ESD	Human Body Model	±2	V	

NOTE: All parameters having Min/Max specifications are guaranteed. Typical values are for information purposes only. Unless otherwise noted, all tests are at the specified temperature and are pulsed tests, therefore: $T_J = T_C = T_A$

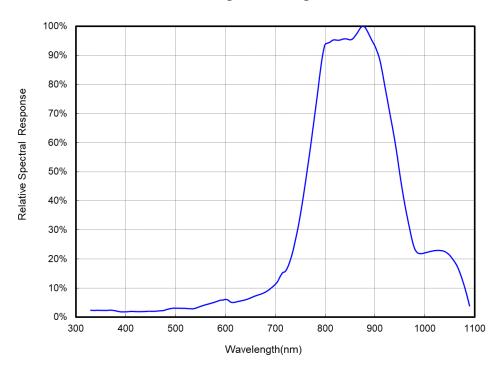
Electrical and Optical Characteristics (T_A=+25°C, unless otherwise specified)

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
I_P	Photo Current	V=5V, λ=850nm, Ee=1mW/cm ²	5.3	6.7	8.1	μΑ
$\lambda_{ m P}$	Wavelength of Peak Sensitivity			870		nm
$\lambda_{10\%}$	Spectral Range of Sensitivity		695		1080	nm
A	Radiant Sensitive Area			1.00		mm^2
LxW	Dimension of Sensitive Area			1.0x1.0		mm×mm
φ	Angle of Half Sensitivity			±55		degree
V _{(BR)R}	Reverse Breakdown Voltage	I _R =100uA, Ee=0mW/cm ²			20	V
I_D	Dark Current	V=5V, Ee=0mW/cm ²		1	15	nA
$S_{\lambda typ}$	Spectral Sensitivity of Chip	λ=850nm		0.67		A/W
η	Quantum Yield of Chip	λ=850nm		0.98		Electron s/Photo
V _{OC}	Open-circuit Voltage	λ =850nm,Ee=1mW/cm ²		340		mV
I_{SC}	Short-circuit Current	λ =850nm,Ee=1mW/cm ²		6.3		μΑ
V_{F}	Forward Voltage	E=0, I _F =80mA		1.2		V
Ct	Total Capacitance	V=0V, Ee=0mW/cm ² , f=1MHz		11		pF
TC_V	Temperature Coefficient of Voc	λ=850nm		-3.1		mV/k
TCI	Temperature Coefficient of I _{SC}	λ=850nm		-0.02		%/k

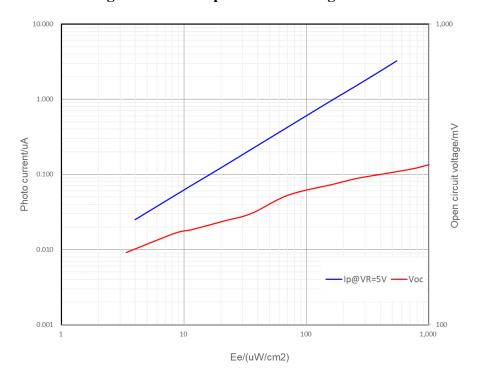


Typical Curves

Relative Spectral Response

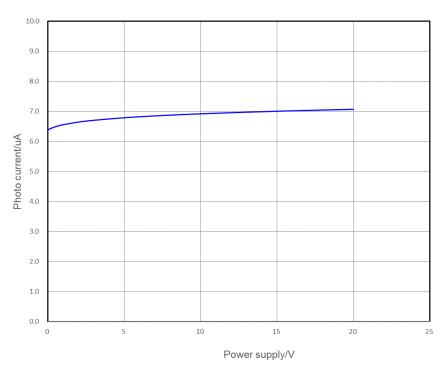


Light Current / Open-circuit Voltage vs. Ee

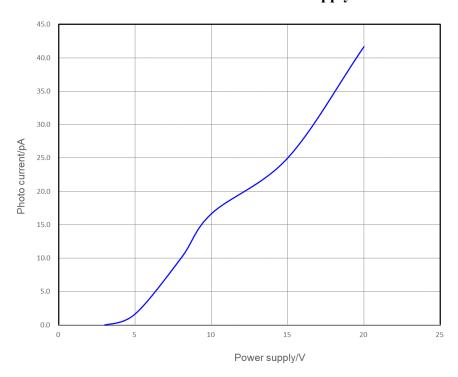




Light Current vs. Power Supply

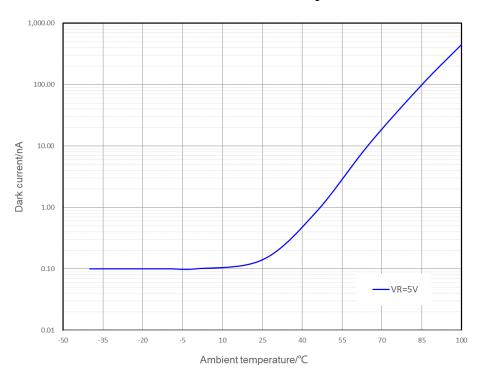


Dark Current vs. Power Supply

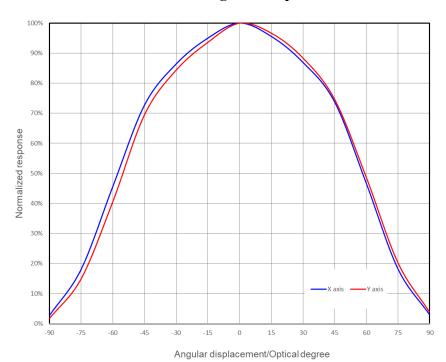




Dark Current vs. Ambient Temperature

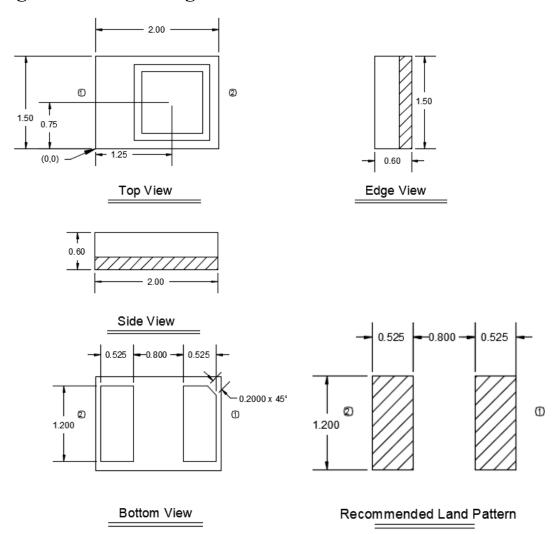


Normalized Angular Response





Package Outline Drawings



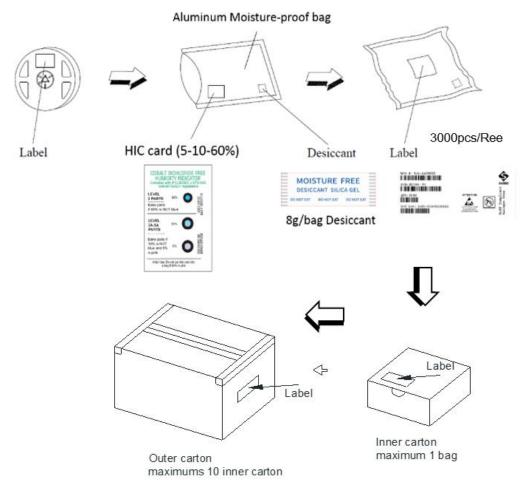
Pin name	n name Pin assignment				
1	Anode				
2	Cathode				

Note:

- [1] All tolerances are +/-0.1mm, unless otherwise noted;
- [2] ALS sensing center is at point A (x,y)=(1.25,0.75);
- [3] Sensitive area: 1.0mm x 1.0mm;
- [4] Unit is mm.



Packaging Quantity Specifications

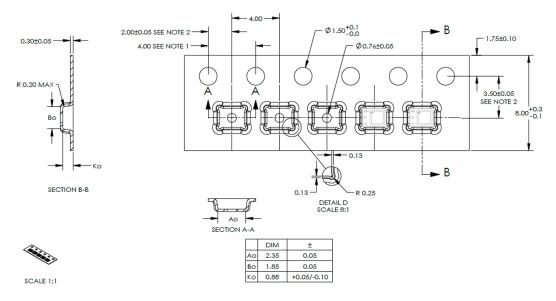


• Dimensions of Reel (Unit: mm)

Width	<u>1</u>	2	3	4	5	6	7	8	9	
7*	178 ± 1	60±0.5	13±0.5	2.2 ± 0.5	3 ±0,5	4 +0.5	5.0 +0.5	9±0.5	11.5±0.5	
	(3)	Ø17	3.0			-1.0±0,2)		1	
4 +11 -22					-1-1:					
			_		F	-i i ')±0.E	//		



• Dimensions of Tape (Unit: mm)



Recommended Method of Storage

Storage is recommended as soon as the bag has been opened to prevent moisture absorption. The following conditions should be observed, if bags are not available:

Storage temperature: 10°C to 30°C
Storage humidity: ≤60%RH max.

• Storage Time: ≤168hr max.

Moisture-Proof Package

To avoid moisture absorption by the resin, the product should be stored under the following conditions:

• Temperature: $23 \pm 5^{\circ}$ C

• Relative humidity: 60% (max)

 Baking is required if the devices have been stored unopened for more than 24 months and the HIC card is not discolored

ESD Precaution

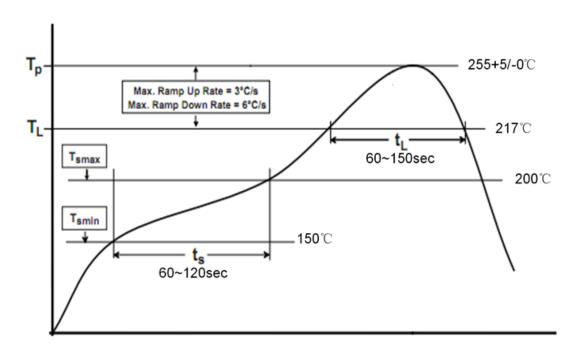
Proper storage and handling procedures should be followed to prevent ESD damage to the devices especially when they are removed from the Anti-static bag. Electro-Static Sensitive Devices warning labels are on the packing.

Make any necessary soldering correction manually

Temperature shall be no more than 350°C (25W for soldering iron) within 3 seconds. Make sure do not do this more than one time for any given pin.



Recommended Solder Profile



Note:

- [1]. Do not put stress on the devices during heating stage while soldering.
- [2]. Do not warp the circuit board after soldering.





Revision History

The revision history provided is for informational purpose only and is believed to be accurate, however, not warranted. Please make sure that you have the latest revision.

Revision Number	Revision Date	Description
0.9B	Nov 17,2023	Add "AEC-Q102 Qualified" in Features
0.9A	Jun 1,2023	"Baking is required if the devices have been store unopened for more than six months" changed into "Baking is required if the devices have been stored unopened for more than 24 months and the HIC card is not discolored".
0.9	Feb 27,2023	Initial Release





IMPORTANT NOTICE

- Right to make changes. Silergy and its subsidiaries (hereafter Silergy) reserve the right to change any information published in this document, including but not limited to circuitry, specification and/or product design, manufacturing or descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products are sold subject to Silergy's standard terms and conditions of sale.
- Applications. Application examples that are described herein for any of these products are for illustrative purposes only. Silergy makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification. Buyers are responsible for the design and operation of their applications and products using Silergy products. Silergy or its subsidiaries assume no liability for any application assistance or designs of customer products. It is customer's sole responsibility to determine whether the Silergy product is suitable and fit for the customer's applications and products planned. To minimize the risks associated with customer's products and applications, customer should provide adequate design and operating safeguards. Customer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Silergy assumes no liability related to any default, damage, costs or problem in the customer's applications or products, or the application or use by customer's third-party buyers. Customer will fully indemnify Silergy, its subsidiaries, and their representatives against any damages arising out of the use of any Silergy components in safety-critical applications. It is also buyers' sole responsibility to warrant and guarantee that any intellectual property rights of a third party are not infringed upon when integrating Silergy products into any application. Silergy assumes no responsibility for any said applications or for any use of any circuitry other than circuitry entirely embodied in a Silergy product.
- Limited warranty and liability. Information furnished by Silergy in this document is believed to be accurate and reliable. However, Silergy makes no representation or warranty, expressed or implied, as to the accuracy or completeness of liable for any indirect, incidental, punitive, special or consequential damages, including but not limited to lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges, whether or not such damages are based on tort or negligence, warranty, breach of contract or any other legal theory. Notwithstanding any damages that customer might incur for any reason whatsoever, Silergy' aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the Standard Terms and Conditions of Sale of Silergy.
- Suitability for use. Customer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of Silergy components in its applications, notwithstanding any applications-related information or support that may be provided by Silergy. Silergy products are not designed, authorized or warranted to be suitable for use in life support, life-critical or safety-critical systems or equipment, nor in applications where failure or malfunction of an Silergy product can reasonably be expected to result in personal injury, death or severe property or environmental damage. Silergy assumes no liability for inclusion and/or use of Silergy products in such equipment or applications and therefore such inclusion and/or use is at the customer's own risk.
- Terms and conditions of commercial sale. Silergy products are sold subject to the standard terms and conditions of commercial sale, as published at http://www.silergy.com/stdterms, unless otherwise agreed in a valid written individual agreement specifically agreed to in writing by an authorized officer of Silergy. In case an individual agreement is concluded only the terms and conditions of the respective agreement shall apply. Silergy hereby expressly objects to and denies the application of any customer's general terms and conditions with regard to the purchase of Silergy products by the customer.
- 6. No offer to sell or license. Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights. Silergy makes no representation or warranty that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right. Information published by Silergy regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from Silergy under the patents or other intellectual property of Silergy.

For more information, please visit: www.silergy.com

© 2023 Silergy Corp.

All Rights Reserved.